## Xu Fang

## List of Publications by Year in descending order

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2258059 2550090 3 28 3 3 citations h-index g-index papers 3 3 3 17 citing authors docs citations times ranked all docs

## VII EANO

#	Article	IF	CITATIONS
1	A Post-Bond TSV Test Method Based on RGC Parameters Measurement. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 506-519.	2.7	12
2	TSV-Defect Modeling, Detection and Diagnosis Based on 3-D Full Wave Simulation and Parametric Measurement. IEEE Access, 2018, 6, 72415-72426.	4.2	9
3	TSV Prebond Test Method Based on Switched Capacitors. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2019, 27, 205-218.	3.1	7